



Material Content Data Sheet



Sales Product Name		ICE2A0565Z		Issued		27. September 2017			
MA#		MA001116330							
Package		PG-DIP-7-4		Weight*		652.92 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	4.468	0.68	0.68	6844	6844	
leadframe	inorganic material	phosphorus	7723-14-0	0.049	0.01		74		
	non noble metal	zinc	7440-66-6	0.194	0.03		297		
	non noble metal	iron	7439-89-6	3.884	0.59		5949		
wire	non noble metal	copper	7440-50-8	157.726	24.16	24.79	241572	247892	
	noble metal	gold	7440-57-5	0.203	0.03	0.03	311	311	
	encapsulation	organic material	carbon black	1333-86-4	1.427	0.22		2186	
plating	plastics	epoxy resin	-	46.156	7.07		70692		
	inorganic material	silicondioxide	60676-86-0	428.249	65.60	72.89	655903	728781	
	leadfinish	non noble metal	tin	7440-31-5	6.540	1.00	1.00	10017	10017
glue	noble metal	silver	7440-22-4	1.911	0.29	0.29	2926	2926	
*deviation	< 10%	plastics	epoxy resin	-	0.316	0.05		484	
		noble metal	silver	7440-22-4	1.792	0.27	0.32	2745	3229
Sum in total:						100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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